



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-04-21</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>giovanni giacopello</b>	<b>Representative Title</b>	<b>ADG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
------------------------------	-------------	----------------------------	-----------------

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA75610LVPDTR	N9ZS*UK79AA6	A	959	2020-04-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	1925	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	CD00331217	

Package Designator	Size	Nbr of instances	Shape	
QFP	15.90,11.00,3.60	36	gull wing	
Comment	PowerSO 36 .43 SLUG UP. MDF valid for CPs: TDA75610LVPD,TDA75610LVPDTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.15	die	76
Lead	11.67	soft solder	6061

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	11.67	Soft solder	6061
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	11.668	Soft solder	974933

Material Composition Declaration :						Mfr Item Name	N925*UK79AA6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	30.044	mg	supplier	die	Silicon(Si)	7440-21-3		28.624	mg	952736	14870
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.188	mg	6257	98
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.017	mg	565	9
				supplier	metallisation	Gold(Au)	7440-57-5		0.044	mg	1465	23
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.146	mg	4860	76
				supplier	metallisation	Tungsten(W)	7440-33-7		0.298	mg	9919	155
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.046	mg	1531	24
				supplier	passivation	Silicon oxide	7631-86-9		0.459	mg	15278	238
				supplier	polymer coating	PIX1 Gamma-butyrolactone	96-48-0		0.222	mg	7389	115
				supplier	alloy & coating	Copper(Cu)	7440-50-8		1232.966	mg	998676	640502
Leadframe	M-004 Copper and its alloys	1234.600	mg	supplier	alloy & coating	Iron(Fe)	7439-89-6		0.568	mg	460	295
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		1.037	mg	840	539
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.029	mg	24	15
				supplier	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	11.668	mg	974933	6061
Soft solder	Solder	11.968	mg	supplier	solder	Silver(Ag)	7440-22-4		0.180	mg	15040	94
				supplier	solder	Tin(Sn)	7440-31-5		0.120	mg	10027	62
Bonding wires	M-004 Copper and its alloys	3.814	mg	supplier	wire	Copper(Cu)	7440-50-8		3.814	mg	1000000	1981
Encapsulation	M-011 Other inorganic materials	638.628	mg	supplier	mold compound	Silica vitreous	60676-86-0		565.186	mg	885000	293603
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		33.847	mg	53000	17583
				supplier	mold compound	Phenol resin	205830-20-2		25.545	mg	40000	13270
				supplier	mold compound	Epoxy type resin	proprietary		12.773	mg	20000	6635
				supplier	mold compound	Carbon black	1333-86-4		1.277	mg	2000	663
connections coating	Solder	5.946	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.946	mg	1000000	3089